

### General Description

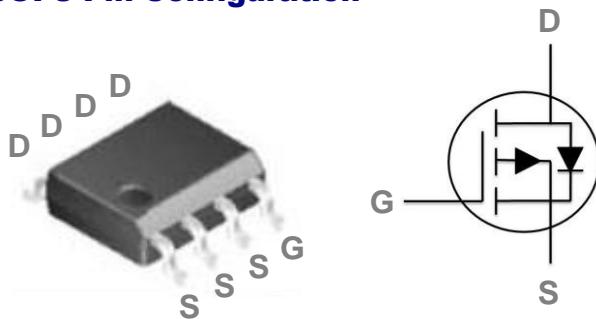
These P-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

BVDSS	RDS(ON)	ID
-60V	47mΩ	-4A

### Features

- -60V,-4A, RDS(ON) 47mΩ @VGS = -10V
- Improved dv/dt capability
- Fast switching
- Green Device Available

### SOP8 Pin Configuration



### Applications

- Networking
- Load Switch
- LED applications

### Absolute Maximum Ratings (Tc=25°C unless otherwise noted)

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	-60	V
V <sub>Gs</sub>	Gate-Source Voltage	±20	V
I <sub>D</sub>	Drain Current – Continuous (T <sub>A</sub> =25°C)	-4	A
	Drain Current – Continuous (T <sub>A</sub> =70°C)	-3.2	A
I <sub>DM</sub>	Drain Current – Pulsed <sup>1</sup>	-16	A
EAS	Single Pulse Avalanche Energy <sup>2</sup>	58	mJ
IAS	Single Pulse Avalanche Current <sup>2</sup>	-34	A
P <sub>D</sub>	Power Dissipation (T <sub>A</sub> =25°C)	2	W
	Power Dissipation – Derate above 25°C	0.016	W/°C
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction to ambient	---	62.5	°C/W

**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**
**Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_D=-250\mu\text{A}$	-60	---	---	V
$\text{I}_{\text{DSS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=-60\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	-1	$\mu\text{A}$
		$V_{\text{DS}}=-48\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=125^\circ\text{C}$	---	---	-10	$\mu\text{A}$
$\text{I}_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	$\text{nA}$

**On Characteristics**

$\text{R}_{\text{DS(ON)}}$	Static Drain-Source On-Resistance	$V_{\text{GS}}=-10\text{V}$ , $I_D=-4\text{A}$	---	41	47	$\text{m}\Omega$
		$V_{\text{GS}}=-4.5\text{V}$ , $I_D=-3\text{A}$	---	53	64	$\text{m}\Omega$
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$ , $I_D = -250\mu\text{A}$	-1.2	-1.6	-2.5	V
$\text{gfs}$	Forward Transconductance	$V_{\text{DS}}=-10\text{V}$ , $I_S=-1\text{A}$	---	5	---	S

**Dynamic and switching Characteristics**

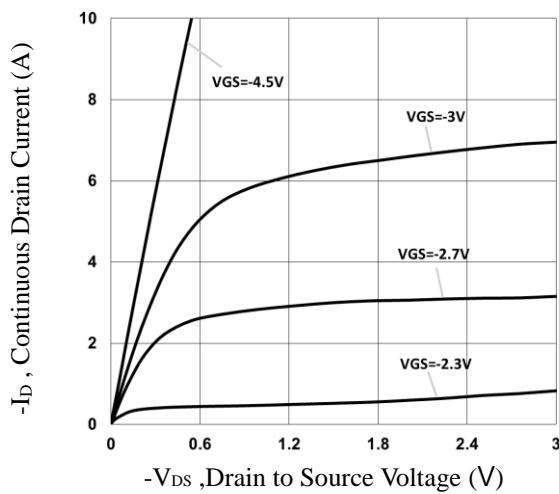
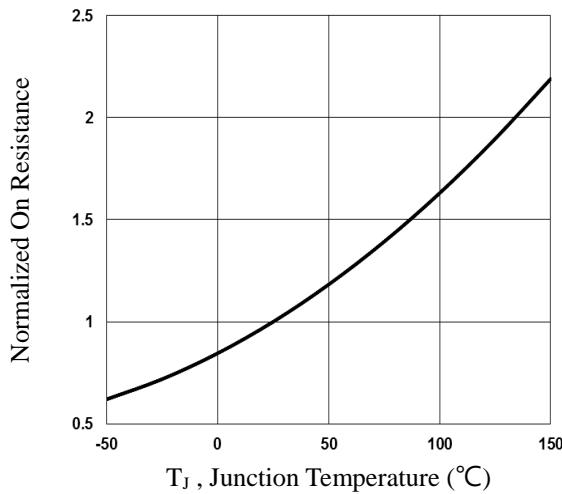
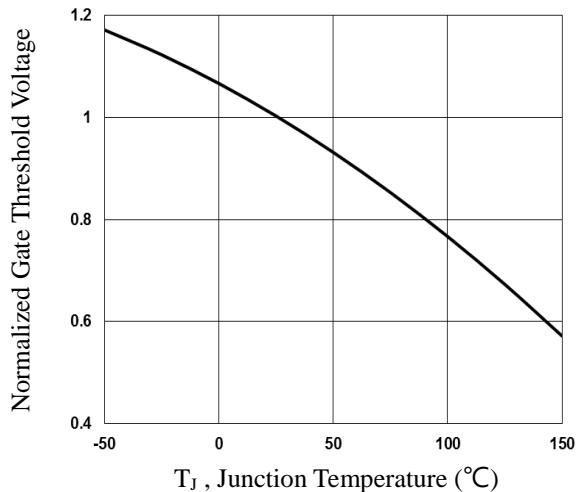
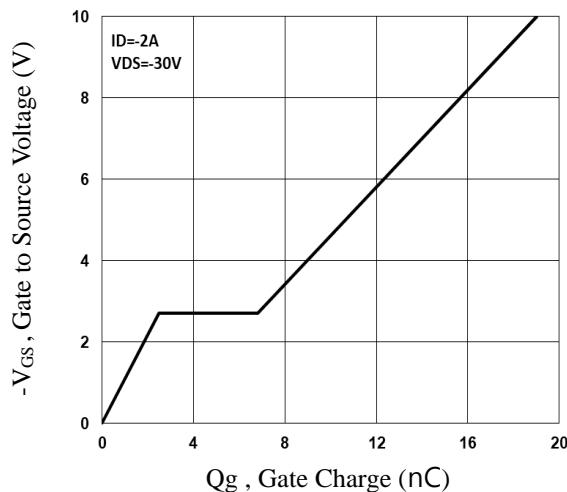
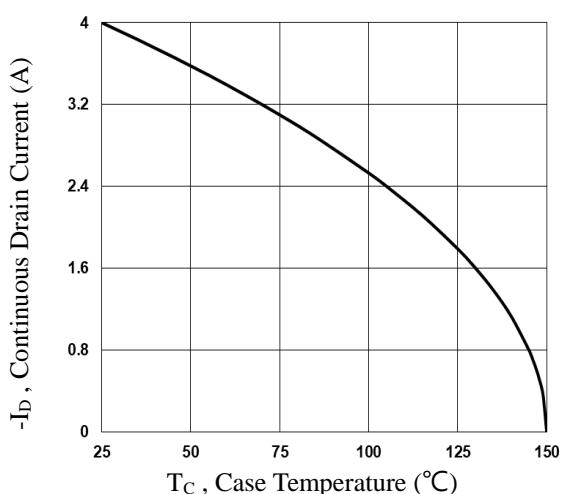
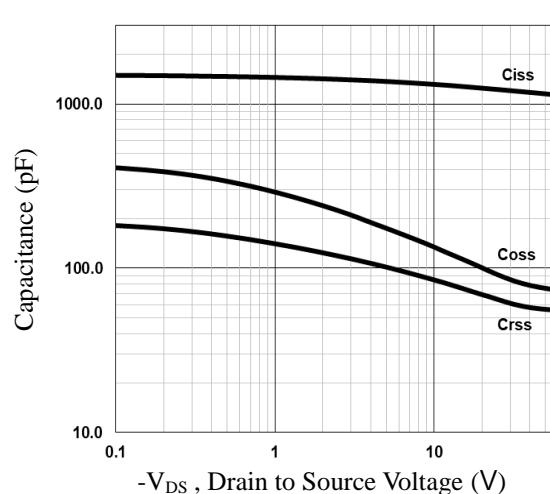
$Q_g$	Total Gate Charge <sup>2, 3</sup>	$V_{\text{DS}}=-30\text{V}$ , $V_{\text{GS}}=-10\text{V}$ , $I_D=-2\text{A}$	---	19	30	nC
$Q_{\text{gs}}$	Gate-Source Charge <sup>2, 3</sup>		---	2.5	3.8	
$Q_{\text{gd}}$	Gate-Drain Charge <sup>2, 3</sup>		---	4.3	6.5	
$T_{\text{d(on)}}$	Turn-On Delay Time <sup>2, 3</sup>	$V_{\text{DD}}=30\text{V}$ , $V_{\text{GS}}=-10\text{V}$ , $R_G=6\Omega$ $I_D=-2\text{A}$	---	18	27	ns
$T_r$	Rise Time <sup>2, 3</sup>		---	8	12	
$T_{\text{d(off)}}$	Turn-Off Delay Time <sup>2, 3</sup>		---	100	150	
$T_f$	Fall Time <sup>2, 3</sup>		---	30	45	
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=-30\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $F=1\text{MHz}$	---	1200	1800	pF
$C_{\text{oss}}$	Output Capacitance		---	85	128	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	60	90	
$R_g$	Gate resistance	$V_{\text{GS}}=0\text{V}$ , $V_{\text{DS}}=0\text{V}$ , $F=1\text{MHz}$	---	14	---	$\Omega$

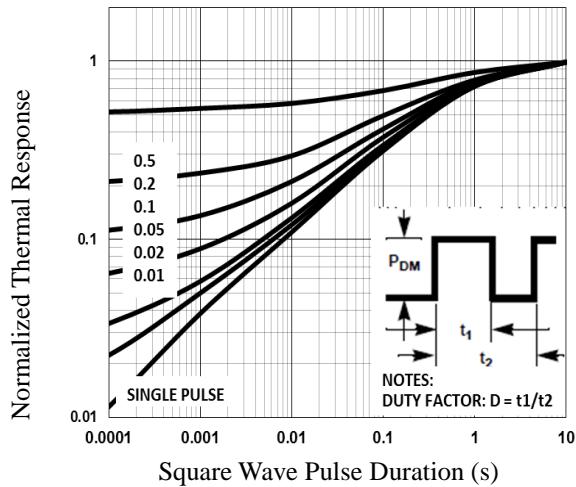
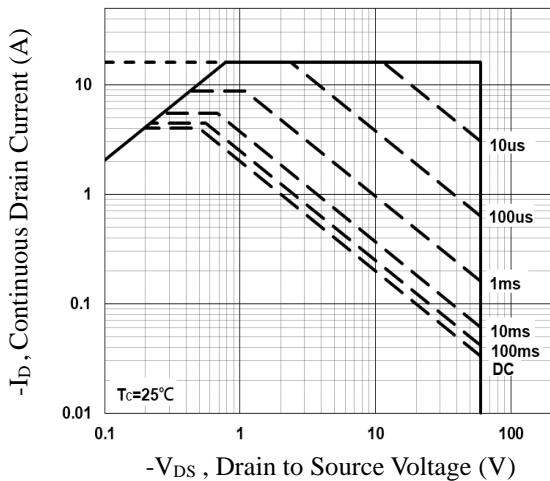
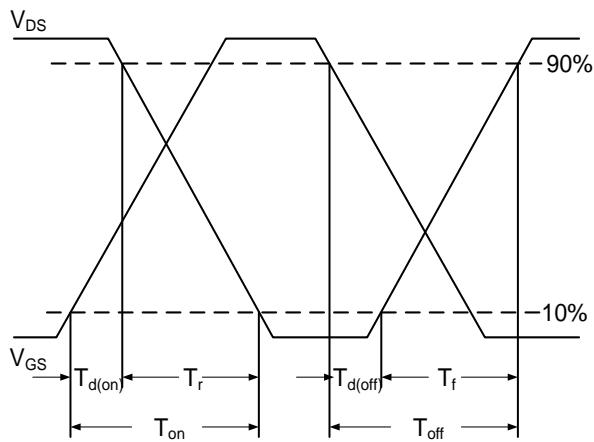
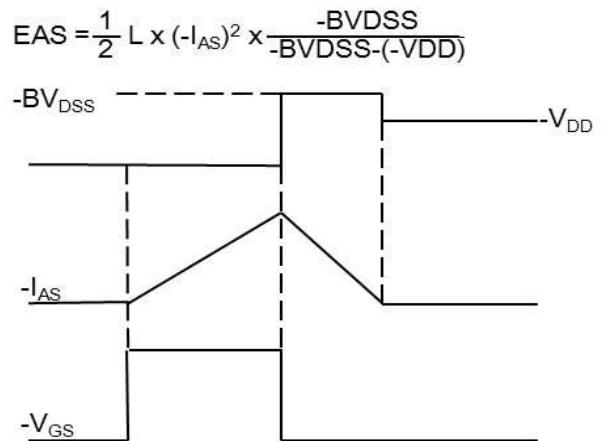
**Drain-Source Diode Characteristics and Maximum Ratings**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current	$V_G=V_D=0\text{V}$ , Force Current	---	---	-4	A
			---	---	-8	A
$V_{\text{SD}}$	Diode Forward Voltage	$V_{\text{GS}}=0\text{V}$ , $I_s=-1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	-1	V
$t_{\text{rr}}$	Reverse Recovery Time	$V_R=-50\text{V}$ , $I_s=-2\text{A}$ $di/dt=100\text{A}/\mu\text{s}$ , $T_J=25^\circ\text{C}$	---	30	---	ns
$Q_{\text{rr}}$	Reverse Recovery Charge		---	20	---	nC

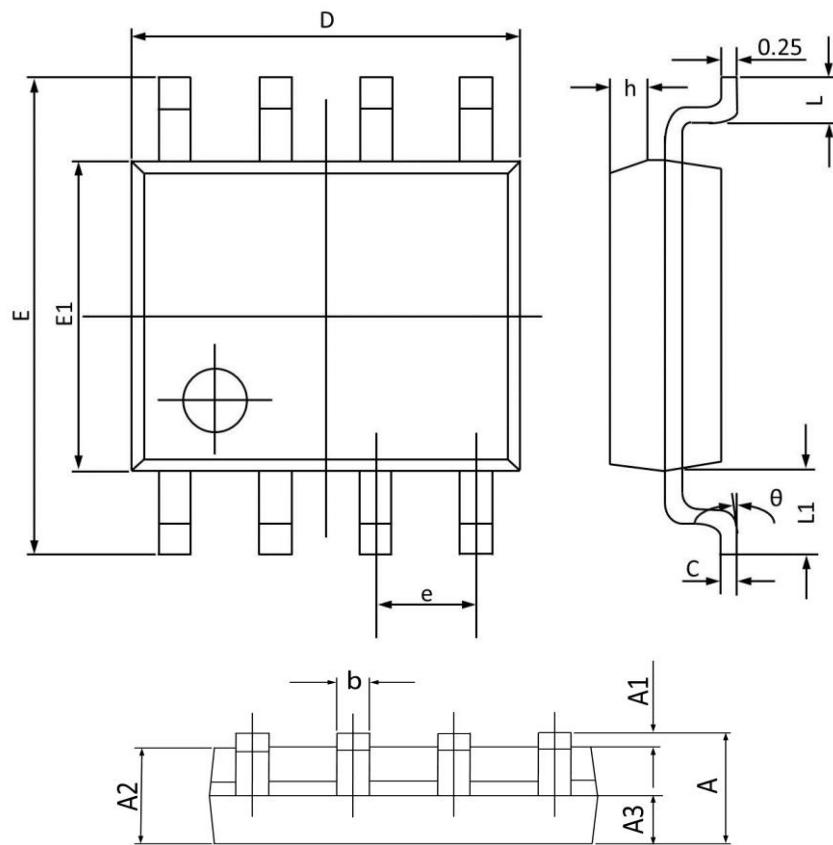
Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2.  $V_{\text{DD}}=-25\text{V}$ ,  $V_{\text{GS}}=-10\text{V}$ ,  $L=0.1\text{mH}$ ,  $I_{\text{AS}}=-34\text{A}$ , Starting  $T_J=25^\circ\text{C}$
3. The data tested by pulsed , pulse width  $\leq 300\text{us}$  , duty cycle  $\leq 2\%$ .
4. Essentially independent of operating temperature.


**Fig.1 Typical Output Characteristics**

**Fig.2 Normalized RDSON vs.  $T_J$** 

**Fig.3 Normalized  $V_{th}$  vs.  $T_J$** 

**Fig.4 Gate Charge Waveform**

**Fig.5 Continuous Drain Current vs.  $T_c$** 

**Fig.6 Capacitance Characteristics**


**Fig.7 Normalized Transient Impedance**

**Fig.8 Maximum Safe Operation Area**

**Fig.9 Switching Time Waveform**

**Fig.10 EAS Waveform**

## SOP8 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.800	0.053	0.069
A1	0.050	0.250	0.002	0.010
A2	1.250	1.650	0.049	0.065
A3	0.500	0.700	0.020	0.028
b	0.300	0.510	0.012	0.020
c	0.150	0.260	0.006	0.010
D	4.700	5.100	0.185	0.201
E	5.800	6.200	0.228	0.244
E1	3.700	4.100	0.146	0.161
e	1.270(BSC)		0.050(BSC)	
h	0.250	0.500	0.010	0.020
L	0.400	1.000	0.016	0.039
L1	1.050(BSC)		0.041(BSC)	
θ	0°	8°	0°	8°